

GCD-010F-CZZ

產品結構Structure

Pure Graphite 0.1μm

Copper Foil Layer 18 μm

Pure Graphite 0.1μm



項目	單位 Unit	度量值Value
基材Substrate	Copper Foil (>99%)	
鍍層 Sputtering	Graphite (<1%)	
鍍層附着強度 Sputtering Strength	%	100
拉伸率 Elongation	%	> 1
耐热温度 Temperature	°C	-40~250
热传导率 Thermal Conductivity(XY*)	W/m•K	>1000
热传导率 Thermal Conductivity (Z*)	W/m•K	>350
表面阻燃Surface Resistance (x-y)	Ω/sq	< 1
垂直阻抗 Contact Resistivity z-	Ω/sq	< 1
幅宽Width	mm	600
厚度Thickness	μm	18+/-5

產品優勢 Features

- 同時具高抗電磁干擾，可充份保護電子元件及減少材料使用厚度。
Meanwhile, it has high anti-electromagnetic interference, which can fully protect electronic components and reduce the thickness of materials.
- 具備良的柔韌度及可返工特性。 It has good flexibility and reworkability.
- 具備遠紅外線幅射散熱效果。 far-infrared radiation heat dissipation effect
- 具優良之任意軸向導熱效果，易與散熱機構組合設計。 It has excellent arbitrary axis conductive thermal effect, and is easy to combine with heat dissipation mechanism

產品應用 Application

- 適用於各類散熱、均熱之解決方案，如手機、筆記型電腦等
- Suitable for all kinds of heat dissipation and heat soaking solutions, such as mobile phones, laptops.
- 熱Buffer 的特性，能快速進行熱轉移，特別適用於短時間瞬時運作之高效率/高功率IC 應用場合。
- The thermal buffer features fast heat transfer, making it ideal for high-efficiency/high-power IC applications with short-term instantaneous operation.

環保測試 Environmental

符合RoHS 與歐盟無鹵標準
RoHS compliant and EU halogen-free

LYE reserve the right to replacement of the main substrate and the protective film and to inform the customer before the replacement.